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(54) Title: A COMPONENT HANDLING ASSEMBLY

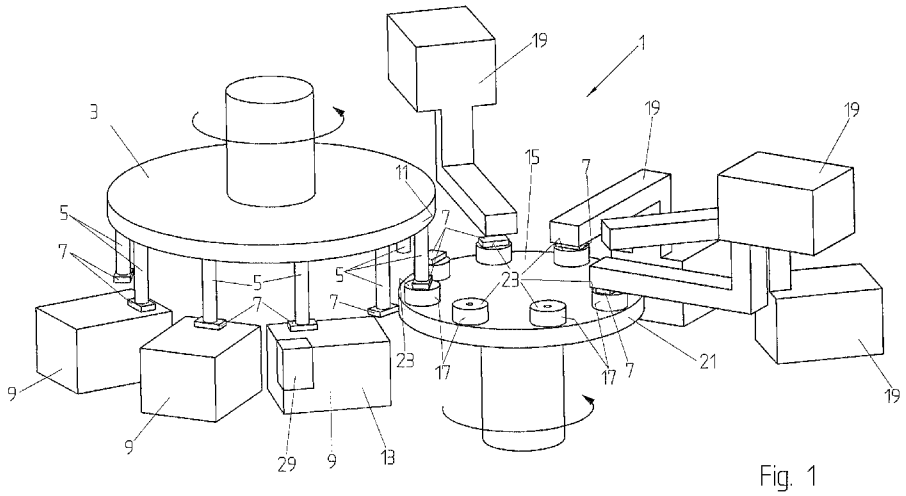


Fig. 1

(57) Abstract: According to the present invention there is provided a component handling assembly, comprising, an index table which comprises one or more nests each of which is configured to cooperate with a component to hold the component as the index table is indexed, wherein the one or more nests are configured such that a component which cooperates with a nest is supported above the nest so that the one or more nests can cooperate with components of various sizes, and an alignment means operable to move a component into a predefined orientation before a component co-operates with a nest on the index table. There is further provided a corresponding method of handling a component.